

NOT RECOMMENDED FOR NEW DESIGN USE DMN3025LFV



DMN3030LFG

N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI3333-8

Product Summary

| BV _{DSS} | R _{DS(ON)} | I _D T _A = +25°C |
|-------------------|-------------------------------|--|
| 30V | 18mΩ @ V _{GS} = 10V | 8.6A |
| 300 | 27mΩ @ V _{GS} = 4.5V | 5.5A |

Description

This new generation MOSFET has been designed to minimize the on-state resistance ($R_{DS(ON)}$) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Backlighting
- DC-DC converters
- Power management functions

Features

- Low R_{DS(ON)} Ensures On-State Losses are Minimized
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- Occupies just 33% of the Board Area Occupied by SO-8 Enabling Smaller End Product
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at

https://www.diodes.com/products/automotive/automotive-products/.

 This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.

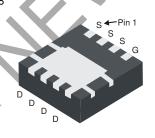
https://www.diodes.com/quality/product-definitions/

Mechanical Data

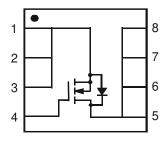
- Package: PowerDI[®]3333-8
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.072 grams (Approximate)







Bottom View



Top View Internal Schematic

Ordering Information (Note 4)

| Part Number | Poskogo | Packing | | |
|---------------|---------------|---------|-------------|--|
| Part Number | Package | Qty. | Carrier | |
| DMN3030LFG-7 | PowerDI3333-8 | 2000 | Tape & Reel | |
| DMN3030LFG-13 | PowerDI3333-8 | 3000 | Tape & Reel | |

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information



N30 = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 22 for 2022) WW = Week Code (01 to 53)

Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

| Characteristic | Symbol | Value | Units | | |
|---|--------------|--|-------|------------|---|
| Drain-Source Voltage | VDSS | 30 | V | | |
| Gate-Source Voltage | Vgss | ±25 | V | | |
| Continuous Drain Current (Note El Ves 10) | Steady State | $T_A = +25$ °C $T_A = +70$ °C | ā | 5.3 4.2 | А |
| Continuous Drain Current (Note 5) V _{GS} = 10V | t < 10s | $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$ | ΙD | 6.8 5.2 | Α |
| Continuous Drain Current (Note C) V 10V | Steady State | $T_A = +25$ °C $T_A = +70$ °C | ID | 8.6 6.8 | Α |
| Continuous Drain Current (Note 6) V _{GS} = 10V | t < 10s | $T_A = +25$ °C $T_A = +70$ °C | lD | 11 8.8 | А |
| Pulsed Drain Current (10µs Pulse, Duty Cycle = 1% | Ірм | 70 | Α | | |
| Maximum Body Diode Continuous Current | | | ls | 3 | Α |

Thermal Characteristics

| Characteristic | | Symbol | Value | Units |
|--|------------------------|------------------|-------|-------|
| Total Power Dissipation (Note 5) | T _A = +25°C | - P _D | 0.9 | W |
| Total Power Dissipation (Note 5) | T _A = +70°C | PD | 0.5 | |
| Thermal Resistance, Junction to Ambient (Note 5) | Steady State | Dov | 148 | °C/W |
| Thermal Resistance, Junction to Ambient (Note 5) | t < 10s | Reja | 89 | |
| Total Power Dissipation (Note 6) | $T_A = +25$ °C | D- | 2.3 | W |
| Total Power Dissipation (Note 6) | T _A = +70°C | P _D | 1.4 | |
| Thermal Resistance, Junction to Ambient (Note 6) | Steady State | Dove | 56 | °C/W |
| Thermal Resistance, Junction to Ambient (Note 6) | t < 10s | Reja | 34 | |
| Thermal Resistance, Junction to Case (Note 6) | Rejc | 6.9 | | |
| Operating and Storage Temperature Range | TJ, TSTG | -55 to +150 | °C | |

Notes:

5. Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate.

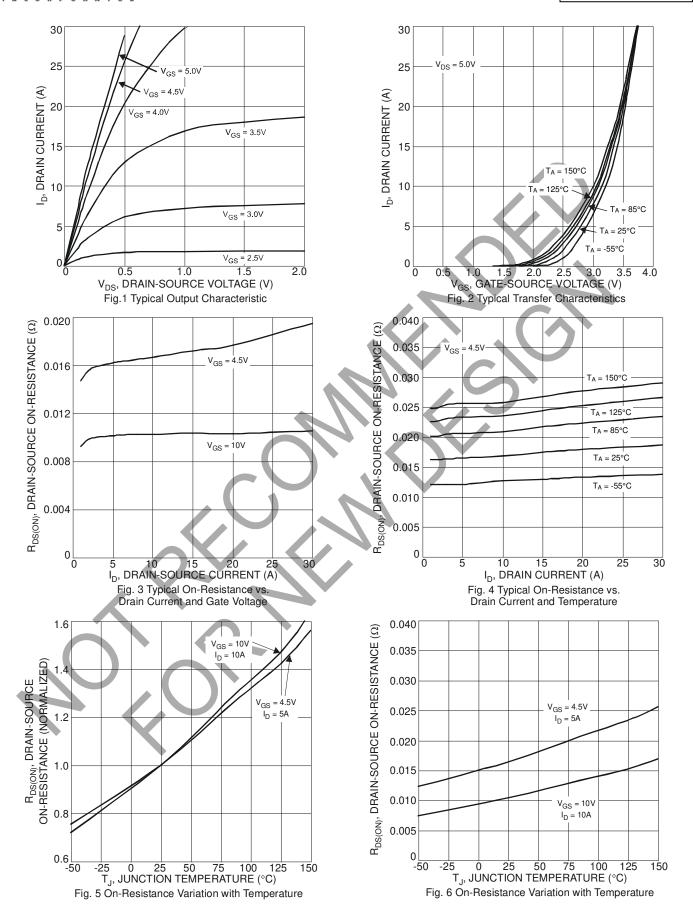


Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

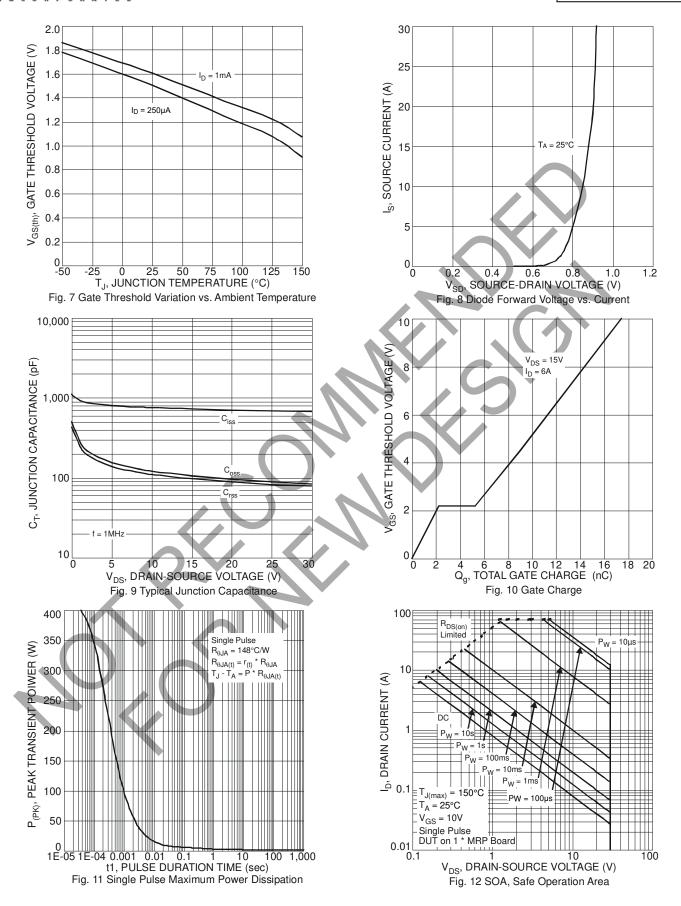
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|--|---------------------|-----|----------|-------------|------|---|--|
| OFF CHARACTERISTICS (Note 7) | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 30 | _ | _ | V | V _{GS} = 0V, I _D = 250μA | |
| Zero Gate Voltage Drain Current T _J = +25°C | IDSS | _ | _ | 100 | nA | $V_{DS} = 30V$, $V_{GS} = 0V$ | |
| Gate-Source Leakage | Igss | _ | _ | ±1 | μΑ | $V_{GS} = \pm 25V$, $V_{DS} = 0V$ | |
| Gale-Source Leakage | | _ | _ | 100 | nA | $V_{GS} = \pm 20V$, $V_{DS} = 0V$ | |
| ON CHARACTERISTICS (Note 7) | | | | | | | |
| Gate Threshold Voltage | V _{GS(TH)} | 8.0 | 1.2 | 2.1 | V | $V_{DS} = V_{GS}$, $I_D = 250\mu A$ | |
| Static Drain-Source On-Resistance | Dagger | | 10 | 18 | mΩ | $V_{GS} = 10V, I_{D} = 10A$ | |
| Static Drain-Source On-Resistance | RDS(ON) | _ | 16 | 27 | mt2 | V _{GS} = 4.5V, I _D = 7.5A | |
| Forward Transfer Admittance | Y _{fs} | _ | 6 | _ | S | V _{DS} = 5V, I _D = 10A | |
| Diode Forward Voltage | V _{SD} | _ | 0.7 | 1.0 | V | $V_{GS} = 0V$, $I_{S} = 1A$ | |
| DYNAMIC CHARACTERISTICS (Note 8) | | | | | | | |
| Input Capacitance | Ciss | - | 751 | 1-1 | | V 40VV 0V | |
| Output Capacitance | Coss | _ | 121 | - | pF | $V_{DS} = 10V$, $V_{GS} = 0V$ f = 1.0MHz | |
| Reverse Transfer Capacitance | Crss | | 110 | 7 | | | |
| Gate Resistance | R_g | _ | 1.5 | _ | Ω | $V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$ | |
| Total Gate Charge V _{GS} = 4.5V | Q_g | | 9 | | | $V_{GS} = 4.5V, V_{DS} = 15V, I_D = 6A$ | |
| Total Gate Charge V _{GS} = 10V | Qg | 1 | 17.4 | _ | | 101/11/11/11 | |
| Gate-Source Charge | Q _{gs} | | 2.2 — nc | | nC | $V_{GS} = 10V, V_{DS} = 15V$ $I_{D} = 6A$ | |
| Gate-Drain Charge | Q_{gd} | 1 | 3 | 7- | | ID = 6A | |
| Turn-On Delay Time | td(on) | | 2.5 | _ | | | |
| Turn-On Rise Time | tR | | 6.6 | | | $V_{DD} = 15V, V_{GS} = 10V$ $R_G = 6\Omega, R_L = 1.8\Omega, I_D = 6.7A$ | |
| Turn-Off Delay Time | tD(OFF) | _ | 19.0 | \ -/ | ns | | |
| Turn-Off Fall Time | t _F | - (| 6.3 | Y | | | |

7. Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to production testing. Notes:

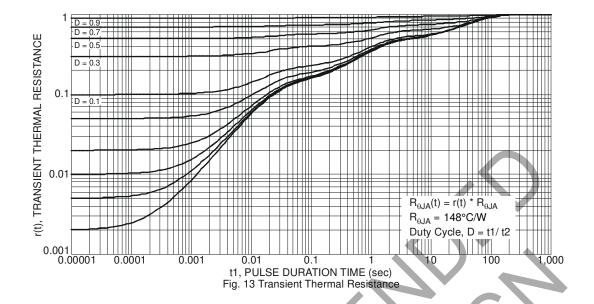










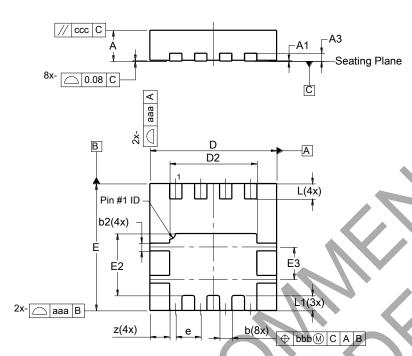




Package Outline Dimensions

 $Please see \ http://www.diodes.com/package-outlines.html \ for the \ latest \ version.$

PowerDI3333-8

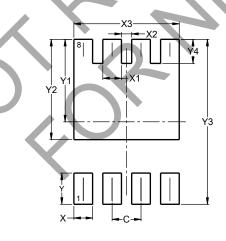


| PowerDI3333-8 | | | | | | |
|----------------------|------|------|-------|--|--|--|
| | | | | | | |
| Dim | Min | Max | Тур | | | |
| Α | 0.75 | 0.85 | 0.80 | | | |
| A1 | 0.00 | 0.05 | 0.02 | | | |
| A 3 | ı | - | 0.203 | | | |
| b | 0.27 | 0.37 | 0.32 | | | |
| b2 | | _ | 0.20 | | | |
| D | 3.25 | 3.35 | 3.30 | | | |
| D2 | 2.22 | 2.32 | 2.27 | | | |
| E | 3.25 | 3.35 | 3.30 | | | |
| E2 | 1.56 | 1.66 | 1.61 | | | |
| E3 | 0.79 | 0.89 | 0.84 | | | |
| е | | | 0.65 | | | |
| 4 | 0.35 | 0.45 | 0.40 | | | |
| L1 | - | _ | 0.39 | | | |
| z | | _ | 0.515 | | | |
| aaa | | 0.25 | | | | |
| bbb | | 0.10 | | | | |
| CCC | 0.10 | | | | | |
| All Dimensions in mm | | | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8



| Dimensions | Value (in mm) | | |
|------------|---------------|--|--|
| C | 0.650 | | |
| X | 0.420 | | |
| X1 | 0.420 | | |
| X2 | 0.230 | | |
| Х3 | 2.370 | | |
| Y | 0.700 | | |
| Y1 | 1.850 | | |
| Y2 | 2.250 | | |
| Y3 | 3.700 | | |
| V4 | 0.540 | | |



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